

**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10028880	12/20/2001	156	272.8	1733 1734	Kilkeny

****APPLICANTS:** Chuang Ta-Ko; Tanaka Sakae;

****CONTINUING DATA VERIFIED:**

BEST AVAILABLE COPY


**** FOREIGN APPLICATIONS VERIFIED:**

TAIWAN 90118342 07/26/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO B-4442 619416-6	

TITLE : Method for bonding an integrated circuit device to a glass substrate

U.S. DEPT. OF COMM. / PAT. & TM. PTO-4361 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claims D.G.	
ISSUE FEE		Primary Examiner	DRAWING		
Amount Due	Date Paid		Sheets Drawn	Figs. Drawn	Print Figs.
		PREPARED FOR ISSUE	Application Examiner		
 TERMINAL DISCLAIMER			WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.		

FILED WITH:

DISK (CRF)

 CD-ROM

(Attached in pocket on right inside flap)